

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of manufacturing an electronic device, the method comprising:

forming an external terminal on an interconnect pattern formed on a substrate;

subsequently mounting a chip component ~~on~~above the substrate face up with an adhesive disposed between the substrate and the chip component, the chip component having an electrode on a first surface of the chip component opposite to a second surface facing the substrate;

forming an insulating section adjacent to the chip component by applying a force between the substrate and the chip component so that a portion of the adhesive is pressed out to a region adjacent to the chip component, the portion having a top higher from the substrate than the first surface, the insulating section formed of the portion of the adhesive; and

forming by inkjet an interconnect on the insulating section from the electrode to the interconnect pattern for electrically connecting the electrode and the interconnect pattern at a temperature lower than a melting point of the external terminal.

2. (Original) The method of manufacturing an electronic device as defined by claim 1,

wherein the interconnect is formed of a dispersant including electrically conductive particles.

3. (Previously Presented) The method of manufacturing an electronic device as defined by claim 2,

wherein the step of forming the interconnect includes ejecting a dispersant including the electrically conductive particles over the insulating section and the interconnect pattern.

4-6. (Canceled)

7. (Original) The method of manufacturing an electronic device as defined by claim 1,

wherein the chip component is a semiconductor element.

8-11. (Canceled)

12. (New) A method of manufacturing an electronic device, the method comprising:

forming an external terminal on an interconnect pattern formed on a substrate;

subsequently mounting a chip component on the substrate face up, the chip component having an electrode on a first surface of the chip component opposite to a second surface facing the substrate and a side surface that is inclined so as to descend in an outward direction from the first surface;

forming an insulating section adjacent to the chip component and on the side surface; and

forming by inkjet an interconnect on the insulating section from the electrode to the interconnect pattern for electrically connecting the electrode and the interconnect pattern at a temperature lower than a melting point of the external terminal.